# Product Information Sheet

**MATERIAL ID:** EPO-TEK® 360T  
**Date:** 02/2007  
**Per:**  
**Rev:** III  
**Material Description:** A two component, high-temperature grade, electrically and thermally insulating epoxy for semiconductor, electronics, fiber optics and medical applications. It is a thixotropic paste for non-flow properties.  
**Number of Components:** Two  
**Mix Ratio by weight:** 100:10  
**Cure Schedule (minimum):** 150°C/1 Minute - 100°C/10 Minutes  
**Specific Gravity:** --- Part A: 1.16 Part B: 1.02  
**Pot Life:** 4 Hours  
**Shelf Life:** Pending  

**NOTE:** Container(s) should be kept closed when not in use. Filled systems should be stirred thoroughly before mixing and prior to use.

**MATERIAL CHARACTERISTICS:** To be used as a guide only, not as a specification. Data below is not guaranteed. Different batches, conditions and applications yield differing results; Cure condition: 150°C/1 hour  
* denotes test on lot acceptance basis

## PHYSICAL PROPERTIES:

*Color (before cure):* Part A: Tan Part B: Amber  
*Consistency:* Thixotropic paste  
*Viscosity (23°C):* 4000 - 6000 cPs  
Thixotropic Index: 5.1  
*Glass Transition Temp:* ≥ 80 °C (Dynamic Cure 20–200°C /ISO 25 Min; Ramp -10–200°C @ 20°C/Min)  
*Coefficient of Thermal Expansion (CTE):*  
Below Tg: 53 x 10⁻⁶ in/in°C  
Above Tg: 146 x 10⁻⁶ in/in°C  
Shore D Hardness: 75  
Lap Shear @ 23°C: 1997 psi  
Die Shear @ 23°C: ≥ 10 Kg / 3,400 psi  
Degradation Temp: 341 °C  
Weight Loss:  
- @ 200°C: 0.59 %  
- @ 250°C: 1.79 %  
- @ 300°C: 4.26 %  
Operating Temp:  
Continuous: - 55°C to + 175°C  
Intermittent: - 55°C to + 275°C  
Storage Modulus @ 23°C: 317,695 psi  
*Particle Size: ≤ 20 microns

## ELECTRICAL AND THERMAL PROPERTIES:

Thermal Conductivity: N/A  
Volume Resistivity @ 23°C: ≥ 2 x 10¹³ Ohm-cm  
Dielectric Constant (1kHz): 3.84  
Dissipation Factor (1kHz): 0.014

## OPTICAL PROPERTIES @ 23°C:

Spectral Transmission: N/A  
Index of Refraction: N/A